2. A system according to Claim 1, wherein the surface is a cylindrical bore, the centralizer comprises non-conductive, circular guide disks located on opposite axial ends of the anode for radially aligning the anode within the cylindrical bore, and the anode is cylindrical.

3. A system according to Claim 1, wherein the seal comprises a seal plate mounted to the anode and a lower portion of the centralizer, the seal plate being located between a lower end of the anode and the lower portion of the centralizer, and a non-conductive lip seal extending around a circumference of the seal plate for retaining the electroplating fluid solution in contact with the anode and the surface of the workpiece.

4. A system according to ~~Claim 1 3, wherein t~~ the lip seal has an inner wall and an outer wall joined at a base, defining a generally U-shaped configuration with the walls extending upward from the base, the inner wall being joined to the seal plate and the outer wall adapted to engage the cylindrical bore of the workpiece.

5. A system according to Claim 1, wherein:

the centralizer comprises an upper disk above the anode and a lower disk below the anode; the cable secures to a lifting connection mounted to the upper disk on the axis of the anode, and

the first wire extends through. an opening in the upper disk to the anode, the opening being offset from the lifting connection.

6. A system according to Claim 1, wherein the anode is continuously moved through the workpiece at a controlled, predetermined rate so that a uniform plating thickness is obtained on the surface over an entire length of the

2. A system according to Claim 1, wherein the surface is a cylindrical bore, the centralizer comprises non-conductive, circular guide disks located on opposite axial ends of the anode for radially aligning the anode within the cylindrical bore, and the anode is cylindrical.

3. A system according to Claim 1, wherein the seal comprises a seal plate mounted to the anode and a lower portion of the centralizer, the seal plate being located between a lower end of the anode and the lower portion of the centralizer, and a non-conductive lip seal extending around a circumference of the seal plate for retaining the electroplating fluid solution in contact with the anode and the surface of the workpiece.

4. A system according to Claim 3, wherein the lip seal has an inner wall and an outer wall joined at a base, defining a generally U-shaped configuration with the walls extending upward from the base, the inner wall being joined to the seal plate and the outer wall adapted to engage the cylindrical bore of the workpiece.

5. A system according to Claim 1, wherein:

the centralizer comprises an upper disk above the anode and a lower disk below the anode; the cable secures to a lifting connection mounted to the upper disk on the axis of the anode, and

the first wire extends through. an opening in the upper disk to the anode, the opening being offset from the lifting connection.

6. A system according to Claim 1, wherein the anode is continuously moved through the workpiece at a controlled, predetermined rate so that a uniform plating thickness is obtained on the surface over an entire length of the